EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	50542	chemical adj mechanical adj polish$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 10:26
S2	500	205/222.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/01 17:40
S3	164	205/222.ccls. and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/01 17:40
S4	95	205/222.ccls. and copper and (polish$3 planar$7)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/01 17:41
S5	36	205/222.ccls. and copper and (polish$3 planar$7) and pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/01 17:41
S6	24	205/222.ccls. and copper and (polish$3 planar$7) and pad and seed$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/01 17:41
S7	14	205/222.ccls. and copper and (polish$3 planar$7) and pad and seed$3 and slurry	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 14:32
S8	32	("5911619"|"6103628"|"6110011"|"6176992"|"6197181"|"6251235"|"6258223"|"6299741"|"6328872"|"6352623"|"6355153"|"6379223"|"6402925"|"6409904"|"6413388"|"6413403").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 11:37

S9	14	205/222.ccls. and copper and (polish$3 planar$7) and pad and seed$3 and slurry	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 12:11
S10	12	S9 not S8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 10:30
S11	44	S10 S8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 10:31
S12	21	laursen-thomas.in. hardikar-vishwas.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 11:01
S14	14	205/222.ccls. and copper and (polish$3 planar$7) and pad and seed$3 and slurry and barrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 14:33
S15	3	205/222.ccls. and copper and (polish$3 planar$7) and pad and seed$3 and slurry and (remove near3 barrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 14:36
S16	2	205/222.ccls. and ((electrodeposit$3 electroplat$3) near3 copper) and (polish$3 planar$7) and pad and seed$3 and slurry and (remove near3 barrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 14:37
S17	1	205/222.ccls. and ((electrodeposit$3 electroplat$3) near3 copper) and (polish$3 planar$7) and pad and seed$3 and slurry and (remove near3 barrier) and (fill$3 near3 feature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 14:38

S18	32	((electrodeposit$3 electroplat$3) near3 copper) and (polish$3 planar$7) and pad and seed$3 and slurry and (remove near3 barrier) and (fill$3 near3 feature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 14:47
S19	3	((electrodeposit$3 electroplat$3) near3 copper) and (polish$3 planar$7) and pad and seed$3 and slurry and (remove near3 barrier) and (fill$3 near3 feature) and (barrier near3 selectivity)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 14:51
S20	1	((electrodeposit$3 electroplat$3) near3 copper) and (polish$3 planar$7) and pad and seed$3 and slurry and (remove near3 barrier) and (fill$3 near3 feature) and (barrier near3 selectivity) and (1:1 "1 to 1")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 14:52
S21	50615	chemical adj mechanical adj polish$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 12:28
S22	379	S21 and (shore near4 hardness)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 12:28
S23	209	S21 and ((shore near4 hardness) with pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 12:45
S24	43	S21 and ((shore near4 hardness) with pad) and selectivity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 12:29
S25	32	S21 and ((shore near4 hardness) with pad) and selectivity and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 12:30

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S26	19	S21 and ((shore near4 hardness) with pad) and selectivity and copper and barrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 17:04
S27	3	S21 and ((shore near4 hardness) with pad) and selectivity and copper and barrier and seed	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 12:32
S28	0	S21 and (((shore near4 hardness) near2 ("less than")) with pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 12:46
S29	0	S21 and (((shore near4 hardness) near2 ("less near2 than")) with pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 12:46
S30	0	S21 and (((shore near4 hardness) near2 (less near2 than)) with pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 12:47
S31	76	S21 and (((shore near4 hardness) near3 (less)) with pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 13:21
S32	71	S21 and (((shore near4 hardness) near3 (less)) with pad) and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 12:48
S33	37	S21 and (((shore near4 hardness) near3 (less)) with pad) and copper and barrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 12:48

S34	17	S21 and (((shore near4 hardness) near3 (less)) with pad) and copper and barrier and seed	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 12:49
S35	16	S34 not S26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 12:49
S36	20	S21 and (((shore near4 hardness) near3 (less)) with pad) and politex	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 13:21
S37	20	S21 and (((shore near4 hardness) near3 (less)) with pad) and politex and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 13:22
S38	17	S21 and (((shore near4 hardness) near3 (less)) with pad) and politex and copper and barrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 13:22
S39	7	S21 and (((shore near4 hardness) near3 (less)) with pad) and politex and copper and barrier and seed	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 13:22
S40	50615	chemical adj mechanical adj polish$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 16:19
S41	129	((slurry solution fluid) near4 "1:1") and S40	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 16:20

S42	78	((slurry solution fluid) near4 "1:1") and S40 and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 16:20
S43	47	((slurry solution fluid) near4 "1:1") and S40 and copper and barrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 16:20
S44	4	(((slurry solution fluid) near4 "1:1") same barrier) and S40 and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 16:22
S45	12	(((slurry solution fluid) near4 ("1:1" "1 to 1" "same rate" "one to one")) same barrier) and S40 and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 16:23
S46	50615	chemical adj mechanical adj polish$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 17:04
S47	185	S46 and copper and barrier and (two adj4 slurry)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/06 17:04
S48	20	LAURSEN-THOMAS.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/29 13:35
S49	2	"6090239".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/29 17:35

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S50	2	"6245676".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/29 16:09
S51	65	platen same CMP same (barrier adj layer) same copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/29 17:35
S52	2778	(soft adj (pad (polishing adj pad)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/29 18:08
S53	688	(soft adj (pad (polishing adj pad))) and (cmp (chemical adj mechanical adj (polishing planarizing)) ecmp (electrochemical adj mechanical adj (polishing planarizing)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/29 18:09
S54	301	(soft adj (pad (polishing adj pad))) and (cmp (chemical adj mechanical adj (polishing planarizing)) ecmp (electrochemical adj mechanical adj (polishing planarizing))) and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/29 18:09
S55	173	(soft adj (pad (polishing adj pad))) and (cmp (chemical adj mechanical adj (polishing planarizing)) ecmp (electrochemical adj mechanical adj (polishing planarizing))) and copper and barrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/29 18:09
S56	148	(soft adj (pad (polishing adj pad))) and (cmp (chemical adj mechanical adj (polishing planarizing)) ecmp (electrochemical adj mechanical adj (polishing planarizing))) and copper and (barrier adj (material layer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/29 18:10
S57	26	(soft adj (pad (polishing adj pad))) and (cmp (chemical adj mechanical adj (polishing planarizing)) ecmp (electrochemical adj mechanical adj (polishing planarizing))) and copper and (barrier adj (material layer)) and (shore near d)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/29 18:14

S58	80	(soft adj (pad (polishing adj pad))) and (cmp (chemical adj mechanical adj (polishing planarizing)) ecmp (electrochemical adj mechanical adj (polishing planarizing))) and copper and (barrier adj (material layer)) and (politex rodel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/29 18:26
S59	38	(soft adj (pad (polishing adj pad))) and (cmp (chemical adj mechanical adj (polishing planarizing)) ecmp (electrochemical adj mechanical adj (polishing planarizing))) and copper and (barrier adj (material layer)) and (politex)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/02 09:29
S60	6	(soft adj (pad (polishing adj pad))) and (ecmp (electrochemical adj mechanical adj (polishing planarizing))) and copper and (barrier adj (material layer)) and (politex)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/02 09:29
S61	2	"6776696".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/02 12:48
S62	2	"6083840".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/02 12:48
S63	101492	"451".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 10:08
S64	34	"451".clas. and (soft with pad) same (copper with (polish polish$3 remov$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 19:26
S65	10	"451".clas. and (soft with pad) same (copper with (polish polish$3 remov$3)) same ((barrier adj layer) tantalum ta)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 12:31

S66	11	("205" "204").clas. and (soft with pad) same (copper with (polish polish$3 remov$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 11:00
S67	2	"6375823".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 11:01
S68	64	((electrochemical electrolytic electrochemically electrolytically) adj (mechanical) adj (plat$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 12:33
S69	0	((electrochemical electrolytic electrochemically electrolytically) adj (mechanical) adj (plat$3)) and (soft adj pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 12:33
S70	6	((electrochemical electrolytic electrochemically electrolytically) adj (mechanical) adj (plat$3)) and (soft with pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 12:33
S71	26	("20020127845" | "5578523" | "5804084" | "5804507" | "5880003" | "5897375" | "5928959" | "5928961" | "5968842" | "6010962" | "6017803" | "6083840" | "6136693" | "6140234" | "6225223" | "6258220" | "6341998" | "6376353" | "6420258" | "6451698" | "6455425" | "6489240" | "6582579").PN. OR ("6884724"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/30 12:36
S72	2	S71 and (soft with pad)	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/30 12:36
S73	8	((451/57).ccls. (438/697).ccls. (205/222).ccls.) and (soft with pad) same (copper with (polish polish$3 remov$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 19:27